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Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



74F620 • 74F623 Inverting Octal Bus Transceiver with 3-STATE Outputs

General Description

These devices are octal bus transceivers designed for asynchronous two-way data flow between the A and B busses. Both busses are capable of sinking 64 mA and have 3-STATE outputs. Dual enable pins (GAB, $\bar{G}BA$) allow data transmission from the A bus to the B bus or from the B bus to the A bus. The 74F620 is an inverting option of the 74F623.

Features

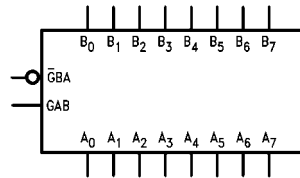
- Designed for asynchronous two-way data flow between busses
- Outputs sink 64 mA
- Dual enable inputs control direction of data flow
- Guaranteed 4000V minimum ESD protection
- 74F620 is an inverting option of the 74F623

Ordering Code:

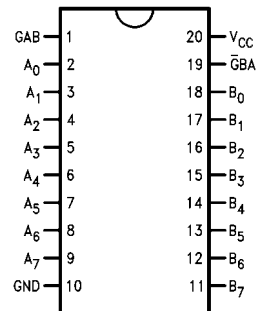
Order Number	Package Number	Package Description
74F620PC	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide
74F623SC	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300 Wide
74F623PC	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Logic Symbol



Connection Diagram



Unit Loading/Fan Out

Pin Names	Description	U.L. HIGH/LOW	Input I_{IH}/I_{IL} Output I_{OH}/I_{OL}
$\overline{G}BA, GAB$	Enable Inputs	1.0/1.0	20 μA /-0.6 mA
A_0-A_7	A Inputs or 3-STATE Outputs	3.5/1.083	70 μA /-0.4 mA
B_0-B_7	B Inputs or 3-STATE Outputs	3.5/1.083	70 μA /-0.4 mA

Functional Description

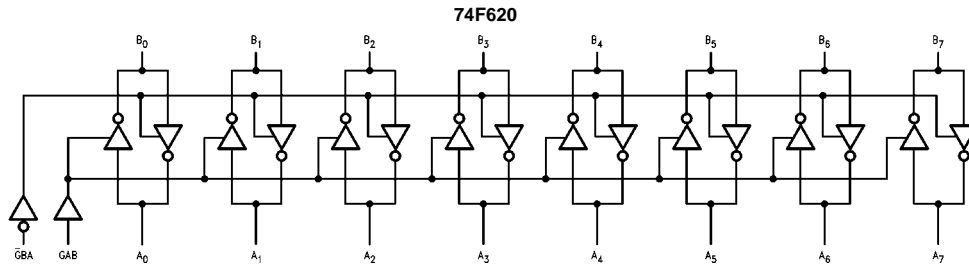
The enable inputs GAB and $\overline{G}BA$ control whether data is transmitted from the A bus to the B bus or from the B bus to the A bus. If both $\overline{G}BA$ and GAB are disabled ($\overline{G}BA$ HIGH and GAB LOW), the outputs are in the high impedance state and data is stored at the A and B busses. When $\overline{G}BA$ is active LOW, B data is sent to the A bus. When GAB is active HIGH, data from the A bus is sent to the B bus. If both enable inputs are active ($\overline{G}BA$ LOW and GAB HIGH) B data is sent to the A bus while A data is sent to the B bus.

Function Table

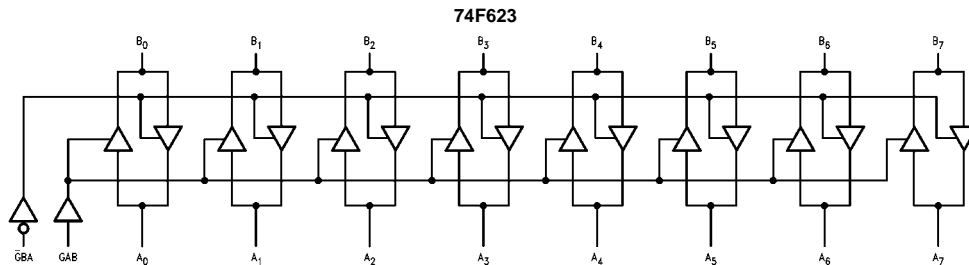
Enable Inputs		Operation	
$\overline{G}BA$	GAB	74F620	74F623
L	L	\overline{B} Data to A Bus	B Data to A Bus
H	H	\overline{A} Data to B Bus	A Data to B Bus
H	L	Z	Z
L	H	\overline{B} Data to A Bus, \overline{A} Data to B Bus	B Data to A Bus, A Data to B Bus

H = HIGH Voltage Level
L = LOW Voltage Level
Z = High Impedance

Logic Diagrams



Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.



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Absolute Maximum Ratings (Note 1)

Storage Temperature	-65°C to +150°C
Ambient Temperature under Bias	-55°C to +125°C
Junction Temperature under Bias	-55°C to +150°C
V _{CC} Pin Potential to Ground Pin	-0.5V to +7.0V
Input Voltage (Note 2)	-0.5V to +7.0V
Input Current (Note 2)	-30 mA to +5.0 mA
Voltage Applied to Output in HIGH State (with V _{CC} = 0V)	
Standard Output	-0.5V to V _{CC}
3-STATE Output	-0.5V to +5.5V
Current Applied to Output in LOW State (Max)	twice the rated I _{OL} (mA)
ESD Last Passing Voltage (Min)	4000V

Recommended Operating Conditions

Free Air Ambient Temperature	0°C to +70°C
Supply Voltage	+4.5V to +5.5V

Note 1: Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

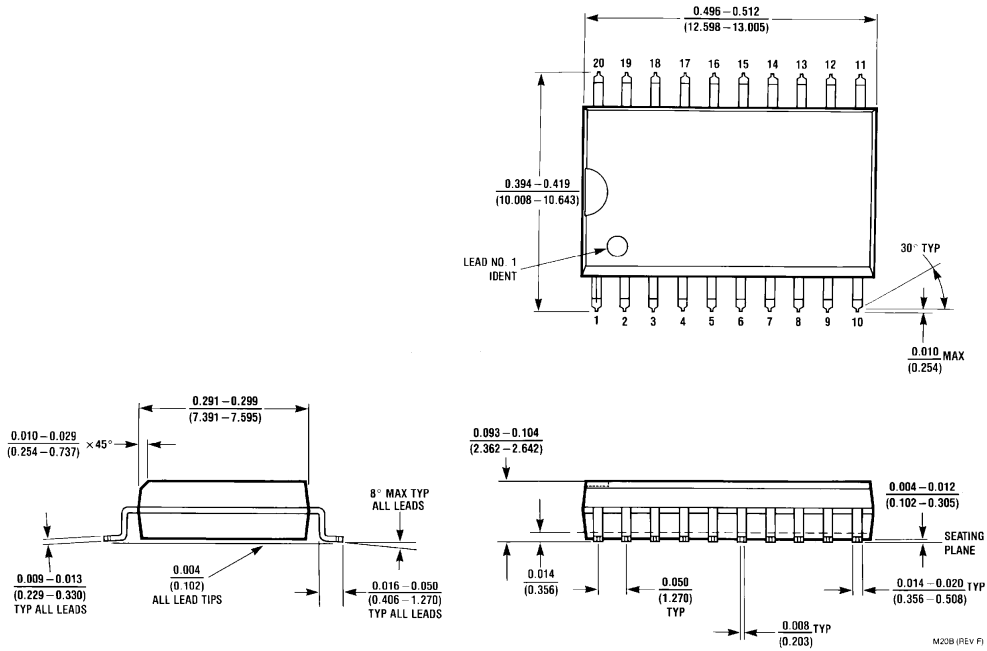
Note 2: Either voltage limit or current limit is sufficient to protect inputs.

DC Electrical Characteristics

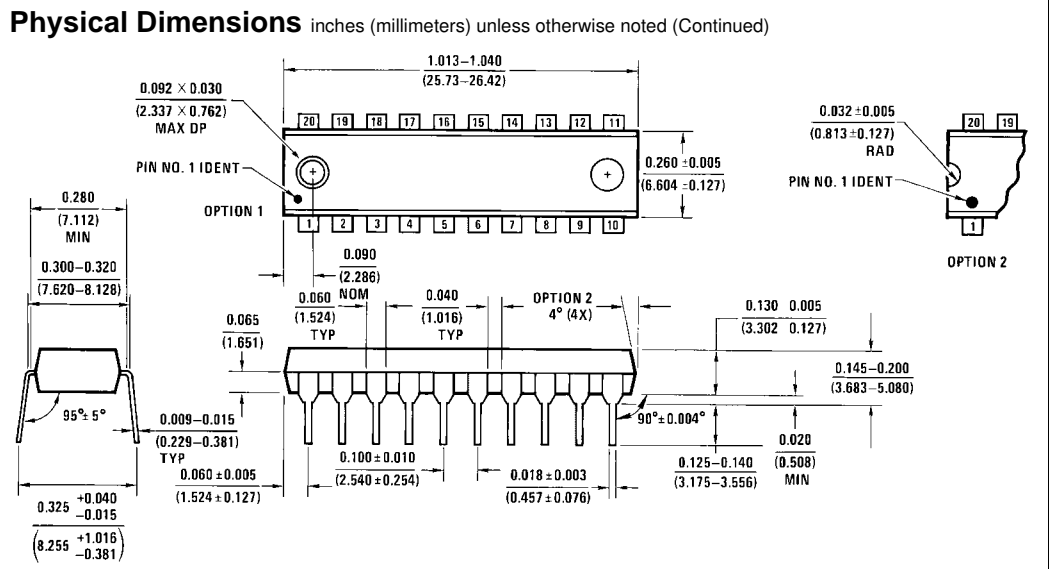
Symbol	Parameter	Min	Typ	Max	Units	V _{CC}	Conditions
V _{IH}	Input HIGH Voltage	2.0			V		Recognized as a HIGH Signal
V _{IL}	Input LOW Voltage			0.8	V		Recognized as a LOW Signal
V _{CD}	Input Clamp Diode Voltage			-1.2	V	Min	I _{IN} = -18 mA (Non I/O Pins)
V _{OH}	Output HIGH Voltage 10% V _{CC}	2.0			V	Min	I _{OH} = -15 mA (A _n , B _n)
V _{OL}	Output LOW Voltage 10% V _{CC}			0.55	V	Min	I _{OL} = 64 mA (A _n , B _n)
I _{IH}	Input HIGH Current			5.0	μA	Max	V _{IN} = 2.7V
I _{BVI}	Input HIGH Current Breakdown Test			7.0	μA	Max	V _{IN} = 7.0V (GBA, GAB)
I _{BVIT}	Input HIGH Current Breakdown (I/O)			0.5	mA	Max	V _{IN} = 5.5V (A _n , B _n)
I _{CEx}	Output HIGH Leakage Current			50	μA	Max	V _{OUT} = V _{CC}
V _{ID}	Input Leakage Test	4.75			V	0.0	I _{ID} = 1.9 μA All Other Pins Grounded
I _{OD}	Output Leakage Circuit Current			3.75	μA	0.0	V _{IOD} = 150 mV All Other Pins Grounded
I _{IL}	Input LOW Current			-0.6	mA	Max	V _{IN} = 0.5V (Non I/O Pins)
I _{IH} + I _{OZH}	Output Leakage Current			70	μA	Max	V _{OUT} = 2.7V (A _n , B _n)
I _{IL} + I _{OZL}	Output Leakage Current			-650	μA	Max	V _{OUT} = 0.5V (A _n , B _n)
I _{OS}	Output Short-Circuit Current	-100		-225	mA	Max	V _{OUT} = 0V
I _{ZZ}	Bus Drainage Test			500	μA	0.0V	V _{OUT} = 5.25V
I _{CCH}	Power Supply Current (74F620)			82	mA	Max	V _O = HIGH, V _{IN} = 0.2V
I _{CCL}	Power Supply Current (74F620)			82	mA	Max	V _O = LOW
I _{CCZ}	Power Supply Current (74F620)			95	mA	Max	V _O = HIGH Z
I _{CCH}	Power Supply Current (74F623)			65	mA	Max	V _O = HIGH
I _{CCL}	Power Supply Current (74F623)			82	mA	Max	V _O = LOW, V _{IN} = 0.2V
I _{CCZ}	Power Supply Current (74F623)			85	mA	Max	V _O = HIGH Z

AC Electrical Characteristics							
Symbol	Parameter	T _A = +25°C V _{CC} = +5.0V C _L = 50 pF			T _A = 0°C to +70°C V _{CC} = +5.0V C _L = 50 pF		Units
		Min	Typ	Max	Min	Max	
t _{PLH}	Propagation Delay	2.5		7.5	2.0	8.0	ns
t _{PHL}	A Input to B Output (74F620)	2.0		7.0	2.0	7.0	
t _{PLH}	Propagation Delay	2.5		7.5	2.0	8.0	ns
t _{PHL}	B Input to A Output (74F620)	2.0		7.0	2.0	7.0	
t _{PLH}	Propagation Delay	1.5		6.5	1.5	7.5	ns
t _{PHL}	A Input to B Output (74F623)	2.0		7.0	2.0	7.5	
t _{PLH}	Propagation Delay	1.5		6.5	1.5	7.5	ns
t _{PHL}	B Input to A Output (74F623)	2.0		7.0	2.0	7.5	
t _{PZH}	Enable Time	2.0		7.0	2.0	8.0	ns
t _{PZL}	GBA Input to A Output	2.5		8.0	2.0	8.5	
t _{PHZ}	Disable Time	1.5		6.5	1.5	7.5	
t _{PLZ}	GBA Input to A Output	1.0		5.5	1.0	5.5	
t _{PZH}	Enable Time	2.0		7.5	2.0	8.5	ns
t _{PZL}	GAB Input to B Output (74F620)	3.0		8.0	2.0	8.5	
t _{PHZ}	Disable Time	2.5		8.0	2.0	9.0	
t _{PLZ}	GAB Input to B Output (74F620)	2.0		7.5	2.0	8.0	
t _{PZH}	Enable Time	2.0		7.5	2.0	8.5	ns
t _{PZL}	GAB Input to B Output (74F623)	2.5		8.0	2.0	8.5	
t _{PHZ}	Disable Time	2.0		8.0	2.0	9.0	
t _{PLZ}	GAB Input to B Output (74F623)	2.0		8.0	2.0	8.0	

Physical Dimensions inches (millimeters) unless otherwise noted



**20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300 Wide
Package Number M20B**



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